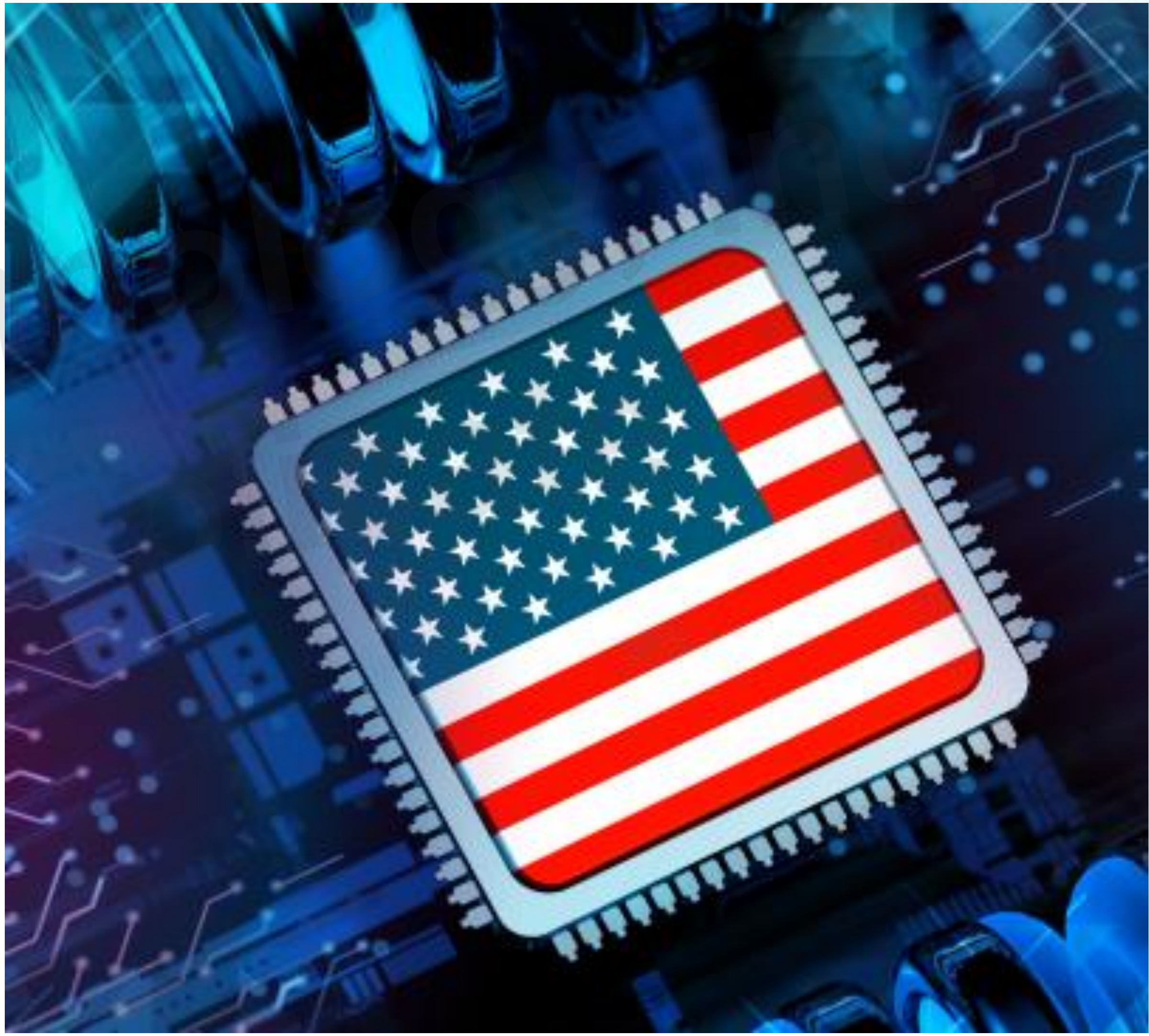
Amkor Technology Arizona Overview

February 2026

Amkor Technology Arizona (ATA)

- Full turnkey (bump/probe/assembly/test)
  - Logistical benefits
  - Fast yield feedback to wafer fab
  - Full USA supply chain capability
  - Supply chain security
- Advanced packaging focus
- Bump and probe local fab support
- High volume manufacturing facility
  - Optimize for minimal variation
- Highest level of automation
- Size
  - Phase 1: 33K sq meters clean room
  - Phase 2: Concept design in progress
  - First option on additional 50 acres adjacent land
- Focus on sustainability
  - 80% water recycling
  - 5MW solar generation on site
  - 50% green power goal



Site Map

Office/Security

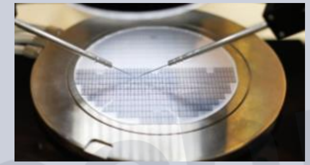
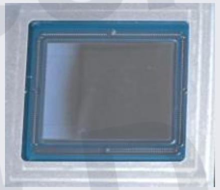
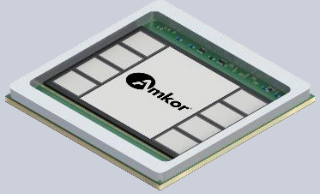
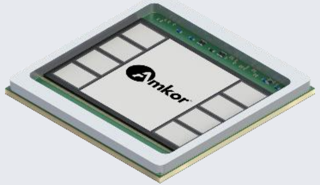
Mnfg Ph 1

Utilities/N2

Site Status

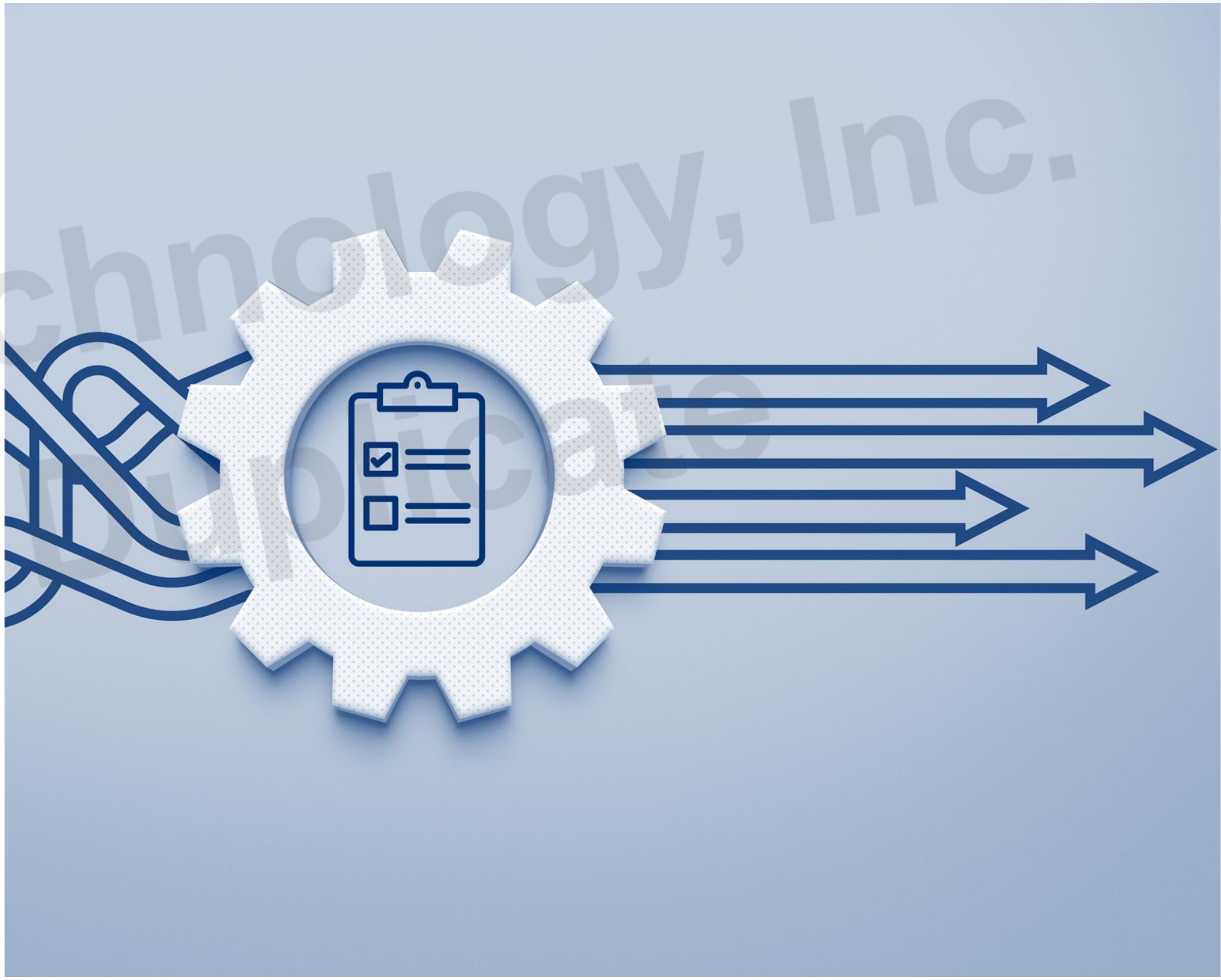
Technology Roadmap for ATA

Schedule Will Be Determined By Customer Demand

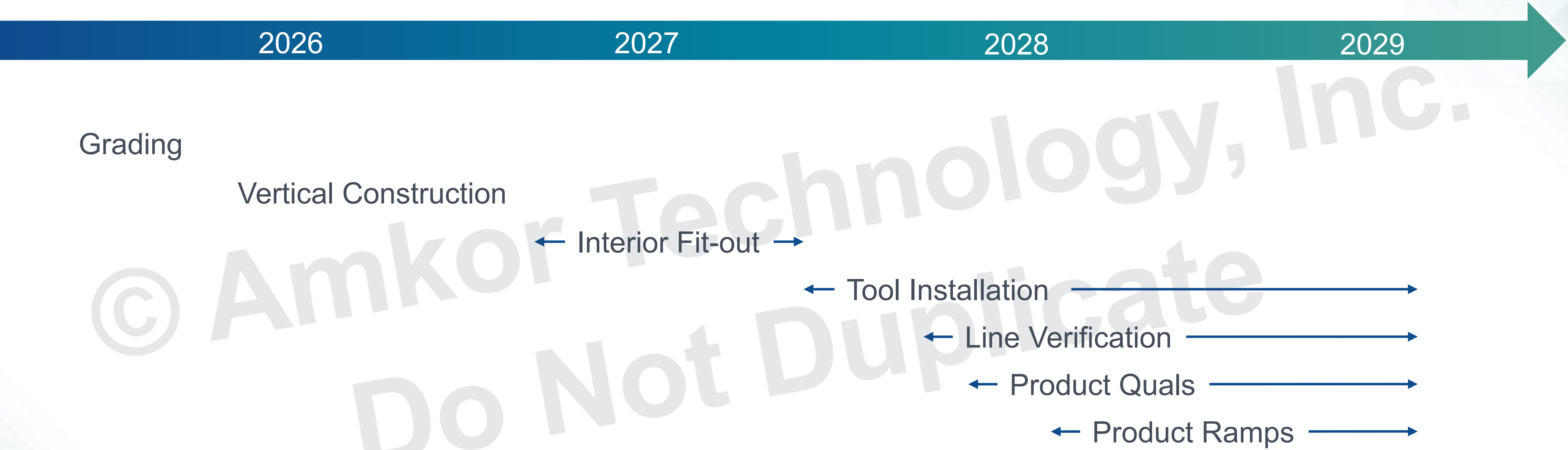
Package Family	Package Technology	
µbump, Bump, Probe (35 ➡ 25 µm pitch D2D for RDL, bridge)		
FCBGA, fcMCM (heterogeneous integration) (mixed pitch 100/45 µm)		
Advanced Wafer Level Packaging (AI, HPC focus) (RDL, bridge)	 Die First, RDL	 Die Last Interposer and RDL
oS and Final Test (110 µm pitch for module to substrate TCB; 130 µm pitch for module to substrate MR)	 Bridge technology	

Updates

- Land purchase for new site executed
- No permit issues
- No power, water issues
- Foundation pour started January 2026
- Steel on-order
- Vertical erection starts May 2026



Construction Status



2026

2027

2028

2029

Grading

Vertical Construction

Interior Fit-out

Tool Installation

Line Verification

Product Quals

Product Ramps

Amkor Technology Arizona Phase 1

Artistic conceptual rendering. Actual design and details may vary and are subject to change.

Amkor Technology®

Thank You

ASSEMBLING
AMERICA'S
FUTURE